

Presentation of Specification to TSG or WG

Presentation to: TSG-RAN Meeting #9

Document for presentation: TR 25.834 Version 1.0.0

Presented for: Information

Abstract of document:

This TR describes the services provided by the physical layer and the layer 2/3 functionality for support of the 1.28 Mcps low chip rate option of UTRA TDD. Based on the protocol structure existing for UTRA TDD / FDD, it is identified which modifications will be required in order to enable the layer 1 characteristics and key features of the low chip rate option.

Changes since last presentation to TSG-RAN Meeting:

First presentation to RAN plenary.

Outstanding Issues:

Contentious Issues: